

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Roy Knechtel et al.
Serial No. : 10/580,361
International Application No. : PCT/DE2004/002638
Filed :
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Title : PRODUCTION OF SEMICONDUCTOR SUBSTRATES
WITH BURIED LAYERS BY JOINING (BONDING)
SEMICONDUCTOR WAFERS
Attorney Docket : LEO 003 PA
Examiner :
Art Unit : CERTIFICATE OF MAILING

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Sir:

PRELIMINARY AMENDMENT

Please preliminary amend the present application, which is the National Stage
entry in the United States of PCT/DE2004/002638, prior to calculation of the filing fee.
Please amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims, which begins
on page 4 of this paper.

Remarks/Arguments begin on page 9 of this paper.